

EDUCATION

- Princeton University**
 Ph.D. in Electrical and Computer Engineering; CGPA: 3.93/4.00

Princeton, NJ
Aug 2024 - Current
- Peking University**
 B. S. in Applied Physics, Department of EECS; CGPA: 89/100 (WES-calculated: 3.81/4.00)

Beijing, China
Sep 2020 - Jul 2024
- University of Michigan**
 Visiting Scholar to Michigan Integrated Circuits Laboratory, Advisor: Prof. David Blaauw

Ann Arbor, MI
Jun 2023 - Dec 2023

SELECTED RESEARCH EXPERIENCE

- Low Power, Energy Efficient Temperature Sensor**
 Research Assistant to: Prof. Xiyuan Tang

Peking University
Feb 2024 - Jun 2024

 - Designed a CMOS temperature sensor in TSMC 28-nm Process
 - Proposed a novel temperature-voltage transducer with high sensitivity and a 12-bit SAR ADC for quantization
- High Efficiency CMOS Digital Transmitter in Localization System**
 Research Assistant to: Prof. David Blaauw

University of Michigan
Jun 2023 - Dec 2023

 - Designed a CMOS Class-D power amplifier in TSMC 180-nm Process, with compact battery and antenna
 - Participated in satellite flyover tests, power amplifier chip measurement
- High Precision, Low Latency Capacitance-to-Digital Converter (CDC)**
 Research Assistant to: Prof. Xiyuan Tang

Peking University
Dec 2022 - Nov 2023

 - Designed a CDC in TSMC 28-nm Process, in cooperation with PhD student Zilong in *PRIME* lab
 - Modeled the $\Delta\Sigma$ loop in MATLAB, designed the FIA amplifier and loop integrator

PUBLICATIONS

- J. Tang and X. Tang, "A 12.6-pJ/Conversion Temperature Sensor with 0.98-mV/K Temperature-Voltage Sensitivity," in *IEEE Transactions on Circuits and Systems II: Express Briefs*, **Accepted**.
- Z. Wang, B. Li, J. Tang, *et al.*, "A 184.8dB FoMs 1.6MS/s Incremental Noise-Shaping Pipeline ADC with Single-Amplification-Based kT/C-Noise-Cancellation Technique," *2025 IEEE International Solid-State Circuits Conference (ISSCC)*, **Accepted**.
- Z. Shen, J. Tang, *et al.*, "A 181.8dB FoMs Zoom Capacitance-to-Digital Converter with kT/C Noise Cancellation and Dead Band Operation," *2024 IEEE Custom Integrated Circuits Conference (CICC)*, Denver, CO, USA, 2024, pp. 1-2.

SKILLS SUMMARY

- Languages:** Mandarin (Native); English
- Programming:** C++, Python, MATLAB
- Circuit Design and Simulation:** Cadence Virtuoso, HSpice, Verilog, Chisel, HFSS

EXTRA-CURRICULUM OUTREACH

- Teaching Assistant for course "Undergraduate Research Practice for Electronic Information Science" Feb, 2024
- Vice President for the Students' Association for Science and Technology Sep, 2022
- Member of department's basketball team at Peking University Sep, 2020

HONORS AND AWARDS

- Merit Student and Third Prize Scholarship at Peking University Sep, 2023
- Third Award in the Final Competition of Integrated Circuit EDA Elite Challenge in China Dec, 2022
- Award for Scientific Research Excellents at Peking University Sep, 2022
- Award for Academic Excellents at Peking University Sep, 2021